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Pre-Release Draft Industry Reviewing Companies That Provided Feedback

Aces
Allion Labs, Inc.
Analogix Semiconductor
BizLink International Corp.
Corning Optical Communications LLC
Cypress Semiconductor
Etron Technology Inc.
Fairchild Semiconductor
Fujitsu Ltd.
Industrial Technology Research Institute (ITRI)
Johnson Components & Equipment Co., Ltd.
Joinsoon Electronics Mfg. Co. Ltd.
JST Mfg. Co., Ltd.
Korea Electric Terminal
Marvell Semiconductor
Motorola Mobility LLC
NEC
Newnex Technology Corp.
NXP Semiconductors
PalCONN/PalNova (Palpilot International Corp.)
Parade Technology
Pericom
Qualcomm
Semtech Corporation
Shenzhen Deren Electronic Co., Ltd.
Silicon Image
Simula Technology Corp.
SMK Corporation
Sony Corporation
Sumitomo Electric Industries
Toshiba Corporation

Revision History

Revision	Date	Description
1.0	August 11, 2014	Initial Release